G11C

STATIC STORES (information storage based on relative movement between record carrier and transducer G11B; semiconductor devices for storage H01L, e.g. H01L 27/108 - H01L 27/11597; pulse technique in general H03K, e.g. electronic switches H03K 17/00)

Definition statement

This place covers:

Devices or arrangements for storage of digital or analogue information in which no relative movement takes place between an information storage element and a transducer; which incorporate a selecting-device for writing-in or reading-out the information into or from the store.

References

Limiting references

This place does not cover:

| Information storage based on relative movement between record carrier and transducer | G11B |
| Manufacturing processes | H01L 21/00, H01L 45/00 |
| Semiconductor devices for storage; layout or structure of memory cells or devices at the fabrication level | H01L 23/00, H01L 27/00, H01L 27/108 - H01L 27/115, H01L 29/00 |
| Pulse technique in general, e.g. electronic switches | H03K 17/00 |
| Using a static store as a picture recording medium | H04N 5/907 |

Application-oriented references

Examples of places where the subject matter of this place is covered when specially adapted, used for a particular purpose, or incorporated in a larger system:

| Solid state disk drives | G06F 3/0679 |
| Record carriers for machines | G06K 19/07 |

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Accessing or allocating memory in electronic computers | G06F 12/00 |

Special rules of classification

In this sub-class there exist three general main groups, G11C 5/00, G11C 7/00 and G11C 8/00, which cover aspects such as power supply, reading and writing arrangements and addressing arrangements that are common to many if not all types of memories. There are further main groups which are dedicated to one or more specific types of memory cell technologies. Within these, there may be specific sub-groups for aspects such as power supply or addressing which parallel the general groups. The convention is that, where a document describes a specific aspect for a specific cell technology without indicating its use with other cell types, it should only be classified under the technology group. If it is described as applicable to two cell types then it should be classified under each cell type and in the general group. Thus, for example, a sense amplifier for a resistive RAM would be classified under
G11C 13/004, while a document applying the same sense amplifier to both ReRAM and flash memory would be further classified in G11C 16/26 and G11C 7/06.

G11C 29/00 is a further general group covering the aspects of testing and repair of memory devices. There are no cell-type specific sub-groups for these aspects and thus they are only classified in this place. However other aspects also covered in testing documents will be classified according to the rules of the previous paragraph.

**Glossary of terms**

In this place, the following terms or expressions are used with the meaning indicated:

<table>
<thead>
<tr>
<th>2D/3D</th>
<th>two/three dimensional</th>
</tr>
</thead>
<tbody>
<tr>
<td>Storage element</td>
<td>an element which can hold at least one item of information and is provided with means for writing-in or reading-out this information</td>
</tr>
<tr>
<td>Memory</td>
<td>a device, including storage elements, which can hold information to be extracted when desired.</td>
</tr>
</tbody>
</table>

**Synonyms and Keywords**

In patent documents, the following abbreviations are often used:

<table>
<thead>
<tr>
<th>ATD</th>
<th>Address transition detection</th>
</tr>
</thead>
<tbody>
<tr>
<td>RAM</td>
<td>Random Access Memory</td>
</tr>
<tr>
<td>DRAM</td>
<td>Dynamic RAM</td>
</tr>
<tr>
<td>FRAM, FeRAM</td>
<td>Ferro-electric RAM</td>
</tr>
<tr>
<td>MRAM</td>
<td>Magnetic RAM</td>
</tr>
<tr>
<td>NVRAM</td>
<td>Nonvolatile RAM</td>
</tr>
<tr>
<td>PCRAM, PRAM</td>
<td>Phase-change RAM</td>
</tr>
<tr>
<td>RRAM, ReRAM</td>
<td>Resistive RAM</td>
</tr>
<tr>
<td>SRAM</td>
<td>Static RAM</td>
</tr>
<tr>
<td>ROM</td>
<td>Read-only Memory</td>
</tr>
<tr>
<td>PROM</td>
<td>Programmable ROM</td>
</tr>
<tr>
<td>EPROM</td>
<td>Erasable PROM</td>
</tr>
<tr>
<td>EEPROM, E2PROM</td>
<td>Electrically-erasable PROM</td>
</tr>
<tr>
<td>EAROM</td>
<td>Electrically-alterable ROM</td>
</tr>
</tbody>
</table>

**G11C 5/00**

Details of stores covered by G11C 11/00

**Definition statement**

This place covers:

Details of arrangements providing supporting functions for semiconductor memory devices, concerning protection against loss of information, memory layout and stacking, signal line and power line interconnection, memory modules and their electrical interconnections, and power supplies including backup supplies, as well as charge pumps, voltage and current reference generators as well as circuits for stabilization of voltages and currents, which are common to all semiconductor memories types covered by subclass G11C, as detailed in main groups G11C 13/00, G11C 14/00.
**Relationships with other classification places**

This group covers the above mentioned aspects only when they are concerned with a semiconductor memory.

Furthermore, in the case where any of the above mentioned aspects are adapted to be used with a semiconductor memory of a specific type, such aspects should be classified in the relevant group covering that specific type of semiconductor device, as long as such a specific group is present.

**References**

**Limiting references**

This place does not cover:

<table>
<thead>
<tr>
<th>Description</th>
<th>Classification(s)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power supplies, reference generators or voltage pumps in general not being concerned with semiconductor memories.</td>
<td>G05F, H02J, H02M</td>
</tr>
<tr>
<td>Circuit means for protection against loss of information in general having no connection to semiconductor memories.</td>
<td>H01L 21/26, G06F 11/00</td>
</tr>
<tr>
<td>Geometrical lay-out of the components in integrated circuits not concerned with semiconductor memories.</td>
<td>H01L 27/0207</td>
</tr>
<tr>
<td>Mechanical aspects of memory modules, supports and cards</td>
<td>H05K 5/02, H01L 25/00</td>
</tr>
</tbody>
</table>

**Application-oriented references**

Examples of places where the subject matter of this place is covered when specially adapted, used for a particular purpose, or incorporated in a larger system:

<table>
<thead>
<tr>
<th>Description</th>
<th>Classification(s)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Protection means for ferromagnetic memories</td>
<td>G11C 11/1695</td>
</tr>
<tr>
<td>Power supply arrangements for ferromagnetic memories</td>
<td>G11C 11/1697</td>
</tr>
<tr>
<td>Protection means for ferroelectric memories</td>
<td>G11C 11/2295</td>
</tr>
<tr>
<td>Power supply arrangements for ferroelectric memories</td>
<td>G11C 11/2297</td>
</tr>
<tr>
<td>Means for protection concerning static memory cells (SRAM)</td>
<td>G11C 11/4125</td>
</tr>
<tr>
<td>Means for protection concerning static memory storage device (SRAM)</td>
<td>G11C11/41355</td>
</tr>
<tr>
<td>Power supply arrangements for SRAMs</td>
<td>G11C11/41357</td>
</tr>
</tbody>
</table>

**Special rules of classification**

If documents are clearly restricted to one specific cell type or memory technology they should not be classified here but in the group of said cell technology, unless there is no group for that cell technology. If documents mention applications to different types of cells then they can be classified here.
G11C 5/025
{Geometric lay-out considerations of storage- and peripheral-blocks in a semiconductor storage device (geometrical lay-out of the components in integrated circuits, H01L 27/0207)}

Definition statement
This place covers:
Geometrical layout considerations of the internal components of a memory device.

References
Limiting references
This place does not cover:

| Geometrical lay-out of the components in integrated circuits | H01L 27/0207 |

Special rules of classification
Layout considerations on a printed circuit board are covered by H05K 1/18.

G11C 5/04
Supports for storage elements {, e.g. memory modules}; Mounting or fixing of storage elements on such supports

Definition statement
This place covers:
Electrical aspects of memory modules such as e.g. SIMM, DIMM or flash memories.

G11C 5/143
{Detection of memory cassette insertion/removal; Continuity checks of supply and ground lines (in general G01R 31/02); Detection of supply variations/interruptions/levels (G11C 5/148 takes precedence); Switching between alternative supplies (back-up supplies per se H02J 9/061), (G11C 5/141 takes precedence)}

Definition statement
This place covers:
Covering the detection of change in supply voltage, on the voltage or the ground side, in general.

References
Limiting references
This place does not cover:

| Battery and back-up supplies | G11C 5/141 |
| Details of power up or power down circuits, standby circuits or recovery circuits | G11C 5/148 |
| Testing of electric apparatus, lines or components, for short-circuits, discontinuities, leakage | G01R 31/02 |
Back-up supplies per se

G11C 5/144
{Detection of predetermined disconnection or reduction of power supply, e.g. power down or power standby}

Definition statement
This place covers:
Voluntary power down or standby arrangements.

G11C 5/148
{Details of power up or power down circuits, standby circuits or recovery circuits}

Definition statement
This place covers:
Covering the characteristics of the power up and power down circuits, the standby circuits and recovery circuits.

G11C 7/00
Arrangements for writing information into, or reading information out from, a digital store (G11C 5/00 takes precedence; auxiliary circuits for stores using semiconductor devices G11C 11/4063, G11C 11/413)

Definition statement
This place covers:
All aspects of reading and writing of data to an address memory cell in general except the addressing of the cell. The addressing and row circuitry is covered in G11C 8/00. G11C 7/00 is more about column and input/output circuitry. "In general" means that technology or cell specific documents are not covered here but in their respective groups.

References

Limiting references
This place does not cover:

<table>
<thead>
<tr>
<th>Details of stores</th>
<th>G11C 5/00</th>
</tr>
</thead>
<tbody>
<tr>
<td>Specific cell types of technologies</td>
<td>G11C 11/00, G11C 17/00</td>
</tr>
<tr>
<td>Auxiliary circuits for stores using semiconductor devices</td>
<td>G11C 11/4063, G11C 11/413</td>
</tr>
<tr>
<td>Higher level memory space management, free space management, garbage collection, cache memories</td>
<td>G06F 12/00</td>
</tr>
<tr>
<td>External memory control circuits, buses, bus protocols, DMA, memory controllers</td>
<td>G06F 13/16</td>
</tr>
<tr>
<td>Encryption, data protection</td>
<td>G06F 2211/007, G06F 12/00</td>
</tr>
</tbody>
</table>
**Application-oriented references**

Examples of places where the subject matter of this place is covered when specially adapted, used for a particular purpose, or incorporated in a larger system:

| Reading and writing arrangements for specific cell types | G11C 11/00 - G11C 17/00 |

**References out of a residual place**

Examples of places in relation to which this place is residual:

| Early solid state music players | G11C 7/16 |

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

| Auxiliary circuits, e.g. for addressing, decoding, driving, writing, sensing or timing | G11C 11/4063 |
| Auxiliary circuits, e.g. for addressing, decoding, driving, writing, sensing, timing, power reduction | G11C 11/413 |
| External data synchronisation during read or write | G06F 13/16 |
| Calibration | G06F 13/16, G11C 29/00 |
| Security aspects, encryption | G06F 2211/007 |
| Amplifiers in general | H03F |
| Basic logic circuits, latches and flip-flops | H03K |
| Delays | H03K 5/00 |
| PLL, DLL circuits per se | H03L |
| Synchronisation | H04L 7/00 |

**Special rules of classification**

If documents are clearly restricted to one specific cell type or memory technology they should not be classified here but in the group of said cell technology, unless there is no group for that cell technology. If documents mention applications to different types of cells then they can be classified here.

**G11C 7/02**

with means for avoiding parasitic signals

**References**

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

| Bit lines or layout aspects | G11C 5/025, G11C 7/12, G11C 7/18 |
| Power supply arrangements | G11C 5/14 |
G11C 7/04

with means for avoiding disturbances due to temperature effects

Special rules of classification
If refresh is concerned G11C 11/406 takes precedence.

G11C 7/062

{Differential amplifiers of non-latching type, e.g. comparators, long-tailed pairs}

Definition statement
This place covers:
Most of the current sense amplifiers (current mirrors based) and most of the multi stage sense amplifiers.

G11C 7/08

Control thereof

Special rules of classification
This is a recent group and most of the material about the control of sense amplifiers in general and about sense amplifier drivers is in G11C 7/06.

G11C 7/10

Input/output [I/O] data interface arrangements, e.g. I/O data control circuits, I/O data buffers

Definition statement
This place covers:
Input/output (I/O) data interface arrangements.

Covers all the synchronous memory data interfaces (Synclink, SDR, DDR, Rambus).

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Level conversion circuits in general | H03K 19/0175 |

Special rules of classification
Serial interfaces (IC2, SPI, single wire) when applied to memories are mainly classified in G11C 5/066. Buses with Ring topologies (daisy chain or peer-to-peer buses) for memories are also covered in G11C 7/10, G11C 7/1051 and G11C 7/1078. Documents where the memory controller is the main aspect are in the G06F 13/16 groups. Data buses and bus protocols in general are in G06F 13/00.
G11C 7/1006
{Data managing, e.g. manipulating data before writing or reading out, data bus switches or control circuits therefor}

Definition statement
This place covers:
In particular:
• Data masking;
• Memories incorporating some form of processing capability from logic function and simple ALUs to memories embedded with a CPU (cache memories are in G06F 12/0802);
• "Sophisticated" data routing, reordering (X-bars).

It also contains sometimes memories with ECC circuits. However these should be searched and classified in G06F 11/1044.

G11C 7/1039
{using pipelining techniques, i.e. using latches between functional memory parts, e.g. row/column decoders, I/O buffers, sense amplifiers}

Definition statement
This place covers:
The pipelining in clock synchronous and wave pipelining in clockless (asynchronous) memories.

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Power supply arrangements for memories with random access ports synchronised on clock signal pulse trains | G11C 7/1072 |

G11C 7/1042
{using interleaving techniques, i.e. read-write of one part of the memory while preparing another part}

Special rules of classification
"Interleaving" when referring to a bit line layout is classified in G11C 7/18.

G11C 7/1045
{Read-write mode select circuits}

Definition statement
This place covers:
Mode setting registers and bonding pads.
References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Redundancy; Test mode entry | G11C 29/00 |

G11C 7/1048

{Data bus control circuits, e.g. precharging, presetting, equalising}

Special rules of classification

Also some on die termination (ODT) documents which are unfortunately spread over three groups G11C 7/1048, G11C 7/1051 and G11C 5/06, where they are now classified.

G11C 7/1051

{Data output circuits, e.g. read-out amplifiers, data output buffers, data output registers, data output level conversion circuits}

Definition statement

This place covers:

Together with G11C 7/1078, most of the synchronous interfaces documents.

G11C 7/1072

{for memories with random access ports synchronised on clock signal pulse trains, e.g. synchronous memories, self timed memories}

Definition statement

This place covers:

Many early SDRAMs but became rapidly obsolete as most dynamic memories are now synchronous.

G11C 7/1075

{for multiport memories each having random access ports and serial ports, e.g. video RAM}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Multiport cells | G11C 8/16 |
**G11C 7/1078**

{Data input circuits, e.g. write amplifiers, data input buffers, data input registers, data input level conversion circuits}

**Definition statement**

*This place covers:*

Together with **G11C 7/1051**, most of the synchronous interfaces documents.

**G11C 7/16**

Storage of analogue signals in digital stores using an arrangement comprising analogue/digital [A/D] converters, digital memories and digital/analogue [D/A] converters

**Definition statement**

*This place covers:*

Also many early solid state music players and early solid state memory cards (e.g. Compact Flash, SDcard). These should not be classified here but in **G11B**, **G06F** and **G06K**.

**G11C 7/22**

Read-write [R-W] timing or clocking circuits; Read-write [R-W] control signal generators or management

**Definition statement**

*This place covers:*

- All the clock generating circuits (PLL, DLL, delay lines, oscillators),
- Overall control of memory operation (delay chains, state machines...) and memory operation mode/state, and
- Control aspects of specific parts of the memory which are not covered in other **G11C 5/00**, **G11C 7/00** and **G11C 8/00** groups.

**Glossary of terms**

*In this place, the following terms or expressions are used with the meaning indicated:*

<table>
<thead>
<tr>
<th>Term</th>
<th>Definition</th>
</tr>
</thead>
<tbody>
<tr>
<td>Dummy cell</td>
<td>cell that is not used for storage but to provide a reference voltage or current during sensing</td>
</tr>
<tr>
<td>Embedded</td>
<td>memories which are designed to be incorporated on the same die as a microcontroller/processor usually in ASICs or System on a Chip circuits - not cache memories</td>
</tr>
<tr>
<td>Burst</td>
<td>Read or Write cycle during which a series of 2, 4, 8 or more external data are sequentially input to or output from the memory device</td>
</tr>
<tr>
<td>Precharge</td>
<td>To prepare the memory for a subsequent read operation (or a write operation) by charging bit lines and/or word lines to a certain voltage</td>
</tr>
</tbody>
</table>
Synonyms and Keywords

In patent documents, the following abbreviations are often used:

<table>
<thead>
<tr>
<th>Abbreviation</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>DPD</td>
<td>Deep Power Down</td>
</tr>
<tr>
<td>DLL</td>
<td>Delay locked loop</td>
</tr>
<tr>
<td>EDO</td>
<td>extended data output</td>
</tr>
<tr>
<td>I/O</td>
<td>Input/Output</td>
</tr>
<tr>
<td>LCD</td>
<td>Liquid Crystal Display</td>
</tr>
<tr>
<td>ODT</td>
<td>On Die Termination</td>
</tr>
<tr>
<td>PLL</td>
<td>Phase locked loop</td>
</tr>
<tr>
<td>SA</td>
<td>Sense Amplifier</td>
</tr>
</tbody>
</table>

In patent documents, the following words/expressions are often used as synonyms:

- "Bit line", "digit line" and "signal line"
- "I/O line" and "data line"
- "Reference cell" and "dummy cell".

G11C 8/00

Arrangements for selecting an address in a digital store (for stores using transistors G11C 11/407, G11C 11/413; {switching or gating circuits for general use H03K 17/00})

Definition statement

This place covers:

Circuitry used for decoding a memory address selecting a row line, a bank, a block or a range of memory cells in a semiconductor memory device.

References

Limiting references

This place does not cover:

<table>
<thead>
<tr>
<th>Reference</th>
<th>Classifications</th>
</tr>
</thead>
<tbody>
<tr>
<td>For memory cells of the field-effect type</td>
<td>G11C 11/407</td>
</tr>
<tr>
<td>Auxiliary circuits, e.g. for addressing, decoding, driving, writing, sensing, timing, power reduction</td>
<td>G11C 11/413</td>
</tr>
<tr>
<td>Shift registers in general, FIFO, LIFO</td>
<td>G11C 19/08, G06F 5/06</td>
</tr>
<tr>
<td>Addressing schemes, architectures or methods, e.g. virtual addressing or multidimensional addressing</td>
<td>G06F 12/00</td>
</tr>
<tr>
<td>Address mapping</td>
<td>G06F 12/02</td>
</tr>
<tr>
<td>Switching or gating circuits for general use</td>
<td>H03K 17/00</td>
</tr>
<tr>
<td>Encoding or decoding method per se</td>
<td>H03M 7/00</td>
</tr>
</tbody>
</table>
**Application-oriented references**

Examples of places where the subject matter of this place is covered when specially adapted, used for a particular purpose, or incorporated in a larger system:

<table>
<thead>
<tr>
<th>Description</th>
<th>Classification</th>
</tr>
</thead>
<tbody>
<tr>
<td>Contact or connection structure for RAS/CAS addressing pins/lines</td>
<td>G11C 5/066</td>
</tr>
<tr>
<td>Circuits selecting Bit lines or data latches (I/O, input-output)</td>
<td>G11C 7/10</td>
</tr>
<tr>
<td>Multiport memory using &quot;single port cells&quot;, i.e where the multiport ability it created e.g. in the I/O circuitry.</td>
<td>G11C 7/1075</td>
</tr>
<tr>
<td>Particular aspects concerning addressing MRAM (ferromagnetic) devices</td>
<td>G11C 11/1653</td>
</tr>
<tr>
<td>Particular aspects concerning addressing FRAM (ferroelectric) devices</td>
<td>G11C 11/2253</td>
</tr>
<tr>
<td>Particular aspects concerning addressing DRAM (dynamic RAM) devices</td>
<td>G11C 11/408</td>
</tr>
<tr>
<td>Particular aspects concerning addressing SRAM (static RAM) devices</td>
<td>G11C 14/1313</td>
</tr>
<tr>
<td>Particular aspects concerning addressing memory devices having resistive memory elements</td>
<td>G11C 13/0023</td>
</tr>
<tr>
<td>Particular aspects concerning addressing circuits of EPROM, EAROM, EEPROM devices or other devices having charge storing memory elements</td>
<td>G11C 16/08</td>
</tr>
</tbody>
</table>

**Special rules of classification**

If documents are clearly restricted to one specific cell type or memory technology they should not be classified here but in the group of said cell technology, unless there is no group for that cell technology. If documents mention applications to different types of cells then they can be classified here.

**G11C 8/04**

using a sequential addressing device, e.g. shift register, counter (using first in first out [FIFO] registers for changing speed of digital data flow G06F 5/06; using last in first out [LIFO] registers for processing digital data by operating upon their order G06F 7/00)

**References**

**Limiting references**

This place does not cover:

<table>
<thead>
<tr>
<th>Description</th>
<th>Classification</th>
</tr>
</thead>
<tbody>
<tr>
<td>Using first in first out [FIFO] registers for changing speed of digital data flow</td>
<td>G06F 5/06</td>
</tr>
<tr>
<td>Using last in first out [LIFO] registers for processing digital data by operating upon their order</td>
<td>G06F 7/00</td>
</tr>
</tbody>
</table>

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Description</th>
<th>Classification</th>
</tr>
</thead>
<tbody>
<tr>
<td>Addressing within memory systems with multidimensional access, e.g. row/column, matrix</td>
<td>G06F 12/0207</td>
</tr>
</tbody>
</table>
G11C 8/08
Word line control circuits, e.g. drivers, boosters, pull-up circuits, pull-down circuits, precharging circuits, for word lines

Definition statement
This place covers:
Circuitries that have an electrical effect on the rows or word lines. e.g. applying a voltage or a potential to the word line or row.

G11C 8/10
Decoders

Definition statement
This place covers:
Decoders, circuitry which processes the address information to make a single or plural selection of word line or row line possible. However, these decoder circuits are usually not used for the electrical activation of the row or word line. This is the task of the word line control circuits.

References
Limiting references
This place does not cover:
Address mapping per se

G11C 8/14
Word line organisation; Word line lay-out

Definition statement
This place covers:
In particular, global and local word line structure.

G11C 8/16
Multiple access memory array, e.g. addressing one storage element via at least independent addressing line groups {(multiport memories in general G11C 7/1075)}

Definition statement
This place covers:
Only documents describing memories where each storage cell on its own has two or more ports.

References
Limiting references
This place does not cover:
Multiport memories in general

G11C 7/1075
G11C 8/18
Address timing or clocking circuits; Address control signal generation or management, e.g. for row address strobe [RAS] or column address strobe [CAS] signals

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Physical realization of a corresponding interface                                                                 | G11C 5/066 |

Synonyms and Keywords
In patent documents, the following words/expressions are often used as synonyms:
• "row" and "word line"

G11C 11/00
Digital stores characterised by the use of particular electric or magnetic storage elements; Storage elements therefor (G11C 14/00 - G11C 21/00 take precedence)

Definition statement
This place covers:
• DRAM (Dynamic RAM), see G11C 11/401 - G11C 11/4099
• FRAM, FeRAM (Ferro-electric RAM) see G11C 11/22
• MRAM (Magnetic RAM) see G11C 11/14 - G11C 11/16
• SRAM (Static RAM) see G11C 11/41 - G11C 11/419
• Multi-level storage, using storage elements with more than two stable states represented by steps, e.g. of voltage, current, phase, frequency, see G11C 11/56.

References
Limiting references
This place does not cover:

| General aspects of power supplies, charge pumps, voltage references and battery backup.                    | G11C 5/00  |
| NVRAM Nonvolatile battery backed up RAM                                                                  | G11C 5/141 |
| General aspects of input/output selection, read and write circuitry.                                      | G11C 7/00  |
| General aspects of address decoding and word line selection.                                              | G11C 8/00  |
| RRAM, ReRAM (Resistive RAM)                                                                               | G11C 13/0002 - G11C 13/0097 |
| PCRAM, PRAM (Phase-change RAM)                                                                             | G11C 13/0004 |
| Digital stores characterised by arrangements of cells having volatile and non-volatile storage properties for back-up when the power is down | G11C 14/00 |
Digital stores in which information comprising one or more characteristic parts is written into the store and in which information is read-out by searching for one or more of these characteristic parts, i.e. associative or content-addressed stores

EPROM (Erasable PROM) EEPROM, E2PROM (Electrically-erasable PROM) EAROM (Electrically-alterable ROM) Flash memory

Erasable programmable read-only memories

Read-only memories programmable only once; Semi-permanent stores, e.g. manually-replaceable information cards

ROM (Read-only Memory)

PROM (Programmable ROM)

Digital stores in which the information is moved stepwise, e.g. shift register

Digital stores in which the information circulates

General aspects of testing.

General aspects of redundancy management.

Informative references
Attention is drawn to the following places, which may be of interest for search:

Sensors

Special rules of classification

G11C 11/56 takes precedence over sub-groups G11C 11/02 - G11C 11/54.

The sub-group classification G11C 11/34 is not to be assigned as there exist more specific places for different cell types.

Glossary of terms

In this place, the following terms or expressions are used with the meaning indicated:

2D two dimensional

Synonyms and Keywords

In patent documents, the following abbreviations are often used:

<table>
<thead>
<tr>
<th>Abbreviation</th>
<th>Definition</th>
</tr>
</thead>
<tbody>
<tr>
<td>AFM</td>
<td>Antiferromagnetic</td>
</tr>
<tr>
<td>CPP</td>
<td>Current Perpendicular to Plane</td>
</tr>
<tr>
<td>FeFET</td>
<td>Ferro-electric Field Effect Transistor</td>
</tr>
<tr>
<td>FM</td>
<td>Ferromagnetic</td>
</tr>
<tr>
<td>GMR</td>
<td>Giant Magnetic Resistive</td>
</tr>
<tr>
<td>MTJ</td>
<td>Magnetic Tunnel Junction</td>
</tr>
<tr>
<td>SAF</td>
<td>Synthetic Antiferromagnetic</td>
</tr>
</tbody>
</table>
**G11C 11/005**

{comprising combined but independently operative RAM-ROM, RAM-PROM, RAM-EPROM cells}

**Definition statement**

*This place covers:*

Memories having two distinct arrays of memory elements, one with volatile memory elements and another one with non-volatile memory elements, the latter functioning as a backup memory for the volatile part of the memory.

**References**

**Informative references**

*Attention is drawn to the following places, which may be of interest for search:*

<table>
<thead>
<tr>
<th>Memory type</th>
<th>CPC class</th>
</tr>
</thead>
<tbody>
<tr>
<td>Memories having two types of memory cells or memory elements merged to each other or otherwise combined in the same memory array</td>
<td>G11C 14/00</td>
</tr>
</tbody>
</table>

**G11C 11/02**

using magnetic elements {(using multibit magnetic storage elements G11C 11/5607; counters with magnetic elements H03K 23/76; pulse generators, static switches, logic circuits with such elements H03K 3/45, H03K 17/80, H03K 19/16; measurement of magnetic variables G01R 33/00)}

**References**

**Informative references**

*Attention is drawn to the following places, which may be of interest for search:*

<table>
<thead>
<tr>
<th>Component type</th>
<th>CPC class</th>
</tr>
</thead>
<tbody>
<tr>
<td>Multibit magnetic storage elements</td>
<td>G11C 11/5607</td>
</tr>
<tr>
<td>Measurement of magnetic variables</td>
<td>G01R 33/00</td>
</tr>
<tr>
<td>Pulse generators, static switches, logic circuits</td>
<td>H03K 3/45, H03K 17/80, H03K 19/16</td>
</tr>
<tr>
<td>Counters with magnetic elements</td>
<td>H03K 23/76</td>
</tr>
</tbody>
</table>

**G11C 11/06**

using single-aperture storage elements, e.g. ring core; using multi-aperture plates in which each individual aperture forms a storage element

**Definition statement**

*This place covers:*

Also the (now obsolete) magnetic-core memories.
**G11C 11/14**

using thin-film elements

**Definition statement**

*This place covers:*

Memories using a single magnetic layer.

Memories using domain wall displacement in a shift register like manner, see also G11C 19/0833.

**References**

*Informative references*

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Magnetic thin film layers per se</th>
<th>H01F 10/00</th>
</tr>
</thead>
<tbody>
<tr>
<td>Manufacturing of a magnetic memory</td>
<td>H01L 29/82</td>
</tr>
</tbody>
</table>

**G11C 11/15**

using multiple magnetic layers *(G11C 11/155 takes precedence)*

**Definition statement**

*This place covers:*

Memories using multiple magnetic layers not using any spin effect.

**References**

*Limiting references*

This place does not cover:

| With cylindrical configuration | G11C 11/155 |

**G11C 11/16**

using elements in which the storage effect is based on magnetic spin effect *(sensors using magnetoresistive multilayer structures G01R 33/093; thin layer magnetic read heads for magnetic discs G11B 5/31; non-reciprocal magnetic elements in waveguides H01P; composition of ferromagnetic material H01F 1/00; gyrators H03H 7/002)*

**Definition statement**

*This place covers:*

Memories using magnetic spin effect, i.e. where the memory elements have magnetic tunnel junctions.

**References**

*Limiting references*

This place does not cover:

| Sensors using magnetoresistive multilayer structures                  | G01R 33/093 |
### Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Topic</th>
<th>CPC</th>
</tr>
</thead>
<tbody>
<tr>
<td>Spin-exchange coupled multilayers per se</td>
<td>H01F 10/32</td>
</tr>
<tr>
<td>Memory structures</td>
<td>H01L 27/22</td>
</tr>
<tr>
<td>Manufacturing of magnetic memory</td>
<td>H01L 27/22</td>
</tr>
</tbody>
</table>

### G11C 11/165

#### {Auxiliary circuits}

**Definition statement**

This place covers:

Auxiliary circuitry for MRAM elements.

**References**

#### Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Topic</th>
<th>CPC</th>
</tr>
</thead>
<tbody>
<tr>
<td>Details of stores</td>
<td>G11C 5/00</td>
</tr>
<tr>
<td>Arrangements for writing information into, or reading information out from, a digital store</td>
<td>G11C 7/00</td>
</tr>
<tr>
<td>Arrangements for selecting an address in a digital store</td>
<td>G11C 8/00</td>
</tr>
</tbody>
</table>

### G11C 11/1653

#### {Address circuits or decoders}

**References**

#### Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Topic</th>
<th>CPC</th>
</tr>
</thead>
<tbody>
<tr>
<td>Arrangements for selecting an address in a digital store</td>
<td>G11C 8/00</td>
</tr>
</tbody>
</table>
G11C 11/1655

{Bit-line or column circuits}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Bit line control circuits, e.g. drivers, boosters, pull-up circuits, pull-down circuits, precharging circuits, equalising circuits, for bit lines | G11C 7/12 |
| Bit line organisation; Bit line lay-out | G11C 7/18 |

G11C 11/1657

{Word-line or row circuits}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Word line control circuits | G11C 8/08 |
| Word line organisation; Word line lay-out | G11C 8/14 |

G11C 11/1659

{Cell access}

Definition statement

This place covers:

MRAM specific details of selecting a memory element, e.g. select transistors, diodes or mere word line or bit line selection voltages.

G11C 11/1673

{Reading or sensing circuits or methods}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Sense amplifiers; Associated circuits | G11C 7/06 |
| Data output circuits, e.g. read-out amplifiers, data output buffers, data output registers, data output level conversion circuits | G11C 7/1051 |
G11C 11/1675

{Writing or programming circuits or methods}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Data input circuits, e.g. write amplifiers, data input buffers, data input registers, data input level conversion circuits | G11C 7/1078 |

G11C 11/1677

{Verifying circuits or methods}

Definition statement

This place covers:

Details of checking written data in MRAM elements.

G11C 11/1693

{Timing circuits or methods}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Read-write (R-W) timing or clocking circuits; Read-write (R-W) control signal generators or management | G11C 7/22 |
| Address timing or clocking circuits; Address control signal generation or management, e.g. for row address strobe (RAS) or column address strobe (CAS) signals | G11C 8/18 |

G11C 11/1695

{Protection circuits or methods}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Memory cell safety or protection circuits, e.g. arrangements for preventing inadvertent reading or writing; Status cells; Test cells | G11C 7/24 |
| Address safety or protection circuits, i.e. arrangements for preventing unauthorised or accidental access | G11C 8/20 |
G11C 11/1697

{Power supply circuits}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Power supply arrangements | G11C 5/14 |

G11C 11/22

using ferroelectric elements {using multibit ferroelectric storage elements G11C 11/5657; pulse generators using ferroelectric elements H03K 3/45; counters using such elements H03K 23/76}

Definition statement

This place covers:

Memories using ferroelectric elements. This covers memories with capacitive elements where the insulating dielectric material between the capacitor plates is a ferroelectric material.

References

Limiting references

This place does not cover:

| Using multibit ferroelectric storage | G11C 11/5657 |
| Pulse generators using ferroelectric elements | H03K 3/45 |
| Counters using such elements | H03K 23/76 |

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Ferroelectric capacitors per se | H01G1/00 |
| Ferroelectric materials | H01G 4/12 |
| Memory structures | H01L 27/11502, H01L 27/11585 |
| Manufacturing of ferroelectric memories | H01L 29/516 |

G11C 11/221

{using ferroelectric capacitors}

Definition statement

This place covers:

Details of FRAM memory elements comprising a ferroelectric capacitor.
**G11C 11/223**

{using MOS with ferroelectric gate insulating film}

**Definition statement**

*This place covers:*
Details of FRAM memory elements comprising a transistor with ferroelectric material, e.g. a FEFET.

**G11C 11/225**

{Auxiliary circuits}

**Definition statement**

*This place covers:*
Auxiliary circuitry for FRAM elements.

**References**

**Informative references**

*Attention is drawn to the following places, which may be of interest for search:*

<table>
<thead>
<tr>
<th>Details of stores</th>
<th>G11C 5/00</th>
</tr>
</thead>
<tbody>
<tr>
<td>Arrangements for writing information into, or reading information out from, a digital store</td>
<td>G11C 7/00</td>
</tr>
<tr>
<td>Arrangements for selecting an address in a digital store</td>
<td>G11C 8/00</td>
</tr>
</tbody>
</table>

**G11C 11/2253**

{Address circuits or decoders}

**References**

**Informative references**

*Attention is drawn to the following places, which may be of interest for search:*

| Arrangements for selecting an address in a digital store | G11C 8/00 |

**G11C 11/2255**

{Bit-line or column circuits}

**References**

**Informative references**

*Attention is drawn to the following places, which may be of interest for search:*

<table>
<thead>
<tr>
<th>Bit line control circuits, e.g. drivers, boosters, pull-up circuits, pull-down circuits, precharging circuits, equalising circuits, for bit lines</th>
<th>G11C 7/12</th>
</tr>
</thead>
<tbody>
<tr>
<td>Bit line organisation; Bit line lay-out</td>
<td>G11C 7/18</td>
</tr>
</tbody>
</table>
G11C 11/2257
{Word-line or row circuits}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Description</th>
<th>CPC Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>Word line control circuits, e.g. drivers, boosters, pull-up circuits, pull-down circuits, precharging circuits, for word lines</td>
<td>G11C 8/08</td>
</tr>
<tr>
<td>Word line organisation; Word line lay-out</td>
<td>G11C 8/14</td>
</tr>
</tbody>
</table>

G11C 11/2259
{Cell access}

Definition statement

This place covers:

FRAM specific details of selecting a memory element, e.g. select transistors, diodes or mere word line or bit line selection voltages.

G11C 11/2273
{Reading or sensing circuits or methods}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Description</th>
<th>CPC Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>Sense amplifiers; Associated circuits</td>
<td>G11C 7/06</td>
</tr>
<tr>
<td>Data output circuits, e.g. read-out amplifiers, data output buffers, data output registers, data output level conversion circuits</td>
<td>G11C 7/1051</td>
</tr>
</tbody>
</table>

G11C 11/2275
{Writing or programming circuits or methods}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Description</th>
<th>CPC Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>Data input circuits, e.g. write amplifiers, data input buffers, data input registers, data input level conversion circuits</td>
<td>G11C 7/1078</td>
</tr>
</tbody>
</table>
G11C 11/2277
{Verifying circuits or methods}

Definition statement
This place covers:
Details of checking written data in MRAM elements.

G11C 11/2293
{Timing circuits or methods}

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Details</th>
<th>Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>Read-write (R-W) timing or clocking circuits; Read-write (R-W) control</td>
<td>G11C 7/22</td>
</tr>
<tr>
<td>signal generators or management</td>
<td></td>
</tr>
<tr>
<td>Address timing or clocking circuits; Address control signal generation</td>
<td>G11C 8/18</td>
</tr>
<tr>
<td>or management, e.g. for row address strobe (RAS) or column address</td>
<td></td>
</tr>
<tr>
<td>address strobe (CAS) signals</td>
<td></td>
</tr>
</tbody>
</table>

G11C 11/2295
{Protection circuits or methods}

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Details</th>
<th>Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>Memory cell safety or protection circuits, e.g. arrangements for</td>
<td>G11C 7/24</td>
</tr>
<tr>
<td>preventing inadvertent reading or writing; Status cells; Test cells.</td>
<td></td>
</tr>
<tr>
<td>Address safety or protection circuits, i.e. arrangements for preventing</td>
<td>G11C 8/20</td>
</tr>
<tr>
<td>unauthorised or accidental access.</td>
<td></td>
</tr>
</tbody>
</table>

G11C 11/2297
{Power supply circuits}

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Details</th>
<th>Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power supply arrangements</td>
<td>G11C 5/14</td>
</tr>
</tbody>
</table>
G11C 11/34

using semiconductor devices {(processes or apparatus for the manufacture or treatment of semiconductor or solid state devices H01L 21/00; integrated circuit devices H01L 27/00; generating electric pulses, e.g. bistable devices using semiconductor devices H03K 3/00)}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Processes or apparatus for the manufacture or treatment of semiconductor or solid state devices | H01L 21/00 |
| Integrated circuit devices | H01L 27/00 |
| Generating electric pulses, e.g. bistable devices using semiconductor devices | H03K 3/00 |

Special rules of classification

Documents should not be classified in this group unless there is no more specific place available below or in G11C 14/00 - G11C 21/00 (see precedence rule at beginning of this main group). e.g., for:

- DRAM (Dynamic RAM), see G11C 11/401 - G11C 11/4099
- FRAM, FeRAM (Ferro-electric RAM) see G11C 11/22
- MRAM (Magnetic RAM) see G11C 11/14 - G11C 11/16
- NVRAM (Nonvolatile RAM) see G11C 5/141 (battery backed RAM) or G11C 16/00 (EAROM/EEPROM/Flash memory)
- PCRAM, PRAM (Phase-change RAM) see G11C 13/0004
- RRAM, ReRAM (Resistive RAM) see G11C 13/0002 - G11C 13/0097
- SRAM (Static RAM) see G11C 11/41 - G11C 11/419
- ROM (Read-only Memory) see G11C 17/02 - G11C 17/126
- PROM (Programmable ROM) see G11C 17/14 - G11C 17/18
- EPROM (Erasable PROM) see G11C 16/00 - G11C 16/349
- EEPROM, E2PROM (Electrically-erasable PROM) see G11C 16/00 - G11C 16/349
- EAROM (Electrically-alterable ROM) see G11C 16/00 - G11C 16/349

G11C 11/401

forming cells needing refreshing or charge regeneration, i.e. dynamic cells

Definition statement

This place covers:

Basically this group covers DRAMs - and some further types of cells needing to be periodically and frequently refreshed such gain cells.
This group and its sub groups concerns mainly DRAM cells of any type from classic one transistor-one capacitor cell types to more exotic types such single transistor cells or gain cells. All cells have in common that they require to be updated or rewritten or refreshed frequently in order to retain their data.

References

Application-oriented references
Examples of places where the subject matter of this place is covered when specially adapted, used for a particular purpose, or incorporated in a larger system:

| Control of displays, e.g. graphic cards | G09G |

Informative references
Attention is drawn to the following places, which may be of interest for search:

| Ferro-electric RAMs or FeRAMs | G11C 11/22 |
| The much less frequent refreshing or updating of data in non-volatile | G11C 16/3418, G11C 13/0021 |
| Fabrication, integration, layout of DRAM cells | H01L 27/108 |

Special rules of classification
This is a technology or cell type specific group and only DRAMs and memories needing frequent refreshes should be classified here. FeRAM with a dynamic mode should be classified in G11C 11/22.

G11C 11/404

with one charge-transfer gate, e.g. MOS transistor, per cell

Definition statement
This place covers:
Mostly 1T1C cells but single transistor cells are also found here (see also G11C 2211/4016 for SOI and isolated well single transistor cells).

G11C 11/405

with three charge-transfer gates, e.g. MOS transistors, per cell

Definition statement
This place covers:
Cells with three charge-transfer gates, but it also contains gain cells and other cells with access transistors combined with another charge storage transistor. Finally, it covers also partially capacitor based cells with two access transistors and those with more than 3 access transistors (multiport DRAM cells see also G11C 8/16).
G11C 11/4072
Circuits for initialisation, powering up or down, clearing memory or presetting

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Initialisation circuits in general | G11C 7/20 |

G11C 11/4074
Power supply or voltage generation circuits, e.g. bias voltage generators, substrate voltage generators, back-up power, power control circuits

Definition statement
This place covers:
All the power supply or voltage generation circuits, e.g. bias voltage generators, substrate voltage generators, back-up power, power control circuits specific to DRAM - see also G11C 5/14-G11C 5/147 for memory power circuits in general; see also G11C 11/4076 and G11C 7/22 for some power management aspects (changing memory state or mode and DPD e.g. deep power down wake-ups) and G11C 11/406 for the refresh aspects in low power mode (self-refresh).

The group contains also most of the documents concerning cells with a controlled back plate and back plate voltage circuits.

G11C 11/4076
Timing circuits (for regeneration management G11C 11/406)

References
Limiting references
This place does not cover:

| Regeneration management | G11C 11/406 |

Informative references
Attention is drawn to the following places, which may be of interest for search:

| For memories with random access ports synchronised on clock signal pulse trains, e.g. synchronous memories, self timed memories | G11C 7/1072 |
| Read-write (R-W) timing or clocking circuits; Read-write (R-W) control signal generators or management | G11C 7/22 |
| Details of clock generating circuits | G11C 7/222 |
| Clock buffers | G11C 7/225 |
**G11C 11/4078**

Safety or protection circuits, e.g. for preventing inadvertent or unauthorised reading or writing; Status cells; Test cells (protection of memory contents during checking or testing **G11C 29/52**)

References

**Limiting references**

This place does not cover:

| Protection of memory contents during checking or testing | **G11C 29/52** |

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

| Safety or protection circuits in general | **G11C 7/24** |

**G11C 11/408**

Address circuits

References

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

| Address circuits in general | **G11C 8/00** |

**G11C 11/4082**

{Address Buffers; level conversion circuits}

References

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

| Address Buffers | **G11C 8/06** |

**G11C 11/4085**

{Word line control circuits, e.g. word line drivers, - boosters, - pull-up, - pull-down, - precharge}

References

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

| Word line control circuits in general | **G11C 8/08** |
G11C 11/4087
(Address decoders, e.g. bit - or word line decoders; Multiple line decoders)

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Address decoders in general | G11C 8/10 |
| Banks | G11C 8/12 |

G11C 11/4091
(Sense or sense/refresh amplifiers, or associated sense circuitry, e.g. for coupled bit-line precharging, equalising or isolating)

Definition statement

This place covers:

Precharging, equalising or isolating circuits for DRAMs are in G11C 11/4094 and in general also in G11C 7/12.

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Sense or sense/refresh amplifiers in general | G11C 7/06 |
| Latching type sense amplifiers | G11C 7/065 |
| Control thereof (sense amplifier drivers) | G11C 7/08 |
| Precharging, equalising or isolating circuits for DRAMs in general | G11C 7/12 |
| Precharging, equalising or isolating circuits for DRAMs | G11C 11/4094 |

G11C 11/4093
(Input/output [I/O] data interface arrangements, e.g. data buffers)

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Input/output (I/O) data interface arrangements in general | G11C 7/10 |
| All the data interface circuits (e.g. Synclink, DDR, Rambus) | G11C 7/10, G11C 7/1051, G11C 7/1078, G11C 7/1072 |
| Level conversion circuits in general | H03K 19/0175 |
G11C 11/4094
Bit-line management or control circuits

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Bit-line management or control circuits in general | G11C 7/12 |

G11C 11/4096
Input/output [I/O] data management or control circuits, e.g. reading or writing circuits, I/O drivers or bit-line switches

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Input/output (I/O) data management or control circuits in general | G11C 7/1048, G11C 7/1051, G11C 7/1078 |

G11C 11/4097
Bit-line organisation, e.g. bit-line layout, folded bit lines

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Bit-line organisation in general | G11C 7/18 |

G11C 11/4099
Dummy cell treatment; Reference voltage generators

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Dummy cell treatment and reference voltage generators in general | G11C 7/14 |

Glossary of terms
In this place, the following terms or expressions are used with the meaning indicated:

| 1T-1C | One transistor one capacitor cells |
| Self-refresh | A power saving memory operation mode in which the refreshes its cells autonomously |
Auto-refresh | An external signal (from a memory controller usually) triggers the refresh, but the rest of the refresh operation is done by circuitry internal to the memory (refresh address counters etc ...)
---|---
Twin cell | Arrangement in which a single datum is stored in two (or more) cells
Gain cell | Cells (usually made of three transistors) in which the charge is stored in a gate electrode of a gain transistor (thereby controlling the conductivity of that transistor),
SOI | Silicon on Insulator - often used to make single transistor DRAM cells (or ZRAM)

**G11C 11/41**

forming {static} cells with positive feedback, i.e. cells not needing refreshing or charge regeneration, e.g. bistable multivibrator or Schmitt trigger

**Definition statement**

*This place covers:*

Memories having memory cells with positive feedback or a latch, i.e. a Static RAM or SRAM. This group only covers the aspects of the memory device itself. Manufacturing is covered by **H01L21/8442** and array structures by **H01L 27/11**.

**G11C 11/412**

using field-effect transistors only {latent image memory **G11C 7/20**; multi-port cells **G11C 8/16**}
References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Auxiliary circuits in general | G11C 5/00, G11C 7/00, G11C 8/00 |

G11C 11/44

using superconductive elements, e.g. cryotron

Definition statement

This place covers:
Memories using superconductive elements like squids

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Pulse generators using such elements | H03K 3/38 |
| For counters | H03K 23/001 |

G11C 11/48

using displaceable coupling elements, e.g. ferromagnetic cores, to produce change between different states of mutual or self-inductance {contains no documents; see G11C 17/00 and subgroups}

Special rules of classification

This sub-group contains no documents; see G11C 17/00 and subgroups.

G11C 11/54

using elements simulating biological cells, e.g. neuron

Definition statement

This place covers:
As used in neural networks.

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Cells storing analogue weights | G11C 27/00 |
| Computer systems based on biological models, e.g. neural networks | G06N 3/00 |
G11C 11/56

using storage elements with more than two stable states represented by steps, e.g. of voltage, current, phase, frequency (counting arrangements comprising multi-stable elements of this type H03K 25/00, H03K 29/00)

Definition statement

This place covers:

Additional aspects relating to the cell type rather than multi-state storage per se should be classified under the relevant cell technology. For counting arrangements comprising multi-stable elements of this type see H03K 25/00, H03K 29/00.

G11C 11/5607

{using magnetic storage elements}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Magnetic storage per se</th>
<th>G11C 11/02 - G11C 11/18</th>
</tr>
</thead>
</table>

G11C 11/5614

{using conductive bridging RAM [CBRAM] or programming metallization cells [PMC]}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Comprising conductive bridging RAM [CBRAM] or programming metallization cells [PMCs]</th>
<th>G11C 13/0011</th>
</tr>
</thead>
</table>

G11C 11/5621

{using charge storage in a floating gate}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Comprising cells containing floating gate transistors</th>
<th>G11C 16/0408</th>
</tr>
</thead>
</table>
G11C 11/5628

{Programming or writing circuits; Data input circuits}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Programming or data input circuits | G11C 16/10 |

G11C 11/5635

{Erasing circuits}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Circuits for erasing electrically, e.g. erase voltage switching circuits | G11C 16/14 |

G11C 11/5642

{Sensing or reading circuits; Data output circuits}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Sensing or reading circuits; Data output circuits | G11C 16/26 |

G11C 11/565

{using capacitive charge storage elements}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Forming cells needing refreshing or charge regeneration | G11C 11/401 |

G11C 11/5657

{using ferroelectric storage elements}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

<p>| Using ferroelectric elements | G11C 11/22 |</p>
<table>
<thead>
<tr>
<th>CPC</th>
<th>G11C 11/5664</th>
<th>{using organic memory material storage elements}</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>References</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Informative references</td>
<td>Attention is drawn to the following places, which may be of interest for search:</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Using organic memory material storage elements</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>CPC</th>
<th>G11C 11/5671</th>
<th>{using charge trapping in an insulator}</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>References</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Informative references</td>
<td>Attention is drawn to the following places, which may be of interest for search:</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Comprising cells with charge storage in an insulating layer, e.g. MNOS, SNOS</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>CPC</th>
<th>G11C 11/5678</th>
<th>{using amorphous/crystalline phase transition storage elements}</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>References</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Informative references</td>
<td>Attention is drawn to the following places, which may be of interest for search:</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Comprising amorphous/crystalline phase transition cells</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>CPC</th>
<th>G11C 11/5685</th>
<th>{using storage elements comprising metal oxide memory material, e.g. perovskites}</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>References</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Informative references</td>
<td>Attention is drawn to the following places, which may be of interest for search:</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Comprising metal oxide memory material, e.g. perovskites</td>
</tr>
</tbody>
</table>
G11C 11/5692
{read-only digital stores using storage elements with more than two stable states}

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Read-only memories programmable only once; Semi-permanent stores, e.g. manually-replaceable information cards | G11C 17/00 |

G11C 13/00
Digital stores characterised by the use of storage elements not covered by groups G11C 11/00, G11C 23/00 - G11C 25/00

Definition statement
This place covers:
Digital stores or memories:
• Using elements in which the information is stored in the form of steps of electrical resistance [Ohm], Resistance RAM (RRAM) and auxiliary circuitry therefore; under G11C 13/0002;
• Using elements whose operation depends on chemical change, G11C 13/02 (G11C 13/0009 takes precedence);
• Using nanotube elements, under G11C 13/025;
• Using optical elements, under G11C 13/04;
• Using magneto-optical elements, under G11C 13/06.

Relationships with other classification places
H01L: Semiconductor fabrication means and methods.
G03H: Holographic processes and apparatus.

References
Limiting references
This place does not cover:

| Digital stores in which the storage effect is based exclusively on magnetism e.g. Magnetic RAM (MRAM) | G11C 11/15, G11C 11/16 |

Informative references
Attention is drawn to the following places, which may be of interest for search:

| Bistable switching devices, e.g. Ovshinsky-effect devices | H01L 45/04 |
G11C 13/0002
{using resistive RAM [RRAM] elements}

Definition statement
This place covers:
RRAM storage elements; for MRAM storage elements see G11C 11/15 and G11C 11/16.

G11C 13/0004
{comprising amorphous/crystalline phase transition cells}

Definition statement
This place covers:
RRAM elements in which the electrical resistance change is based on an amorphous to crystalline or crystalline to amorphous transition in a phase change material.

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Multi-state phase transition memory cells | G11C 11/5678 |

G11C 13/0007
{comprising metal oxide memory material, e.g. perovskites}

Definition statement
This place covers:
RRAM elements in which the electrical resistance change is based on a switching mechanism in metal oxides e.g. TiO, NiO, HfO2, CuO.

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Multibit storage elements using metal oxide memory material | G11C 11/5685 |

G11C 13/0009
{RRAM elements whose operation depends upon chemical change}

Definition statement
This place covers:
RRAM elements in which the electrical resistance change is based on the formation and breaking of chemical bonds.
**G11C 13/0011**

{comprising conductive bridging RAM [CBRAM] or programming metallization cells [PMCs]}

**Definition statement**

This place covers:
RRAM elements in which the electrical resistance change is based on ion movement in a solid electrolyte between metal electrodes.

**G11C 13/0014**

{comprising cells based on organic memory material}

**References**

*Informative references*

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Reference Description</th>
<th>CPC Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>Multibit storage elements using organic memory material</td>
<td>G11C 11/5664</td>
</tr>
</tbody>
</table>

**G11C 13/0021**

{Auxiliary circuits}

**Definition statement**

This place covers:
Auxiliary circuitry for RRAM elements.

**References**

*Informative references*

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Reference Description</th>
<th>CPC Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>Details of stores</td>
<td>G11C 5/00</td>
</tr>
<tr>
<td>Arrangements for writing information into, or reading information out from, a digital store</td>
<td>G11C 7/00</td>
</tr>
<tr>
<td>Arrangements for selecting an address in a digital store</td>
<td>G11C 8/00</td>
</tr>
</tbody>
</table>

**G11C 13/0023**

{Address circuits or decoders}

**References**

*Informative references*

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Reference Description</th>
<th>CPC Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>Arrangements for selecting an address in a digital store</td>
<td>G11C 8/00</td>
</tr>
</tbody>
</table>
G11C 13/0026
{Bit-line or column circuits}

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Bit line control circuits, e.g. drivers, boosters, pull-up circuits, pull-down circuits, precharging circuits, equalising circuits, for bit lines | G11C 7/12 |
| Bit line organisation; Bit line lay-out | G11C 7/18 |

G11C 13/0028
{Word-line or row circuits}

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Word line control circuits, e.g. drivers, boosters, pull-up circuits, pull-down circuits, precharging circuits, for word lines | G11C 8/08 |
| Word line organisation; Word line lay-out | G11C 8/14 |

G11C 13/0038
{Power supply circuits}

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Power supply arrangements | G11C 5/14 |

G11C 13/004
{Reading or sensing circuits or methods}

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Sense amplifiers; Associated circuits | G11C 7/06 |
| Data output circuits, e.g. read-out amplifiers, data output buffers, data output registers, data output level conversion circuits | G11C 7/1051 |
G11C 13/0059

{Security or protection circuits or methods}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Topic</th>
<th>CPC Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>Memory cell safety or protection circuits, e.g. arrangements for preventing inadvertent reading or writing; Status cells; Test cells</td>
<td>G11C 7/24</td>
</tr>
<tr>
<td>Address safety or protection circuits, i.e. arrangements for preventing unauthorised or accidental access</td>
<td>G11C 8/20</td>
</tr>
</tbody>
</table>

G11C 13/0061

{Timing circuits or methods}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Topic</th>
<th>CPC Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>Read-write (R-W) timing or clocking circuits; Read-write (R-W) control signal generators or management</td>
<td>G11C 7/22</td>
</tr>
<tr>
<td>Address timing or clocking circuits; Address control signal generation or management, e.g. for row address strobe (RAS) or column address strobe (CAS) signals</td>
<td>G11C 8/18</td>
</tr>
</tbody>
</table>

G11C 13/0069

{Writing or programming circuits or methods}

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Topic</th>
<th>CPC Code</th>
</tr>
</thead>
<tbody>
<tr>
<td>Data input circuits, e.g. write amplifiers, data input buffers, data input registers, data input level conversion circuits</td>
<td>G11C 7/1078</td>
</tr>
</tbody>
</table>

G11C 13/02

using elements whose operation depends upon chemical change
({G11C 13/0009 takes precedence}; using electrochemical charge G11C 11/00)

Definition statement

This place covers:

Storage elements in which the electrical resistance change is based on the formation and breaking of chemical bonds (for RRAM G11C 13/0009 takes precedence).
References

Limiting references

This place does not cover:

| Using electrochemical charge | G11C.11/00 |

G11C 13/06

using magneto-optical elements ({G11C 13/042 takes precedence} magneto-optics in general G02F)

References

Limiting references

This place does not cover:

| Using information stored in the form of an interference pattern | G11C 13/042 |
| Using magnetic-optical storage elements | G11C 13/043 |

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Magneto-optics in general | G02F |

Synonyms and Keywords

In patent documents, the following abbreviations are often used:

| CBRAM | Conductive Bridging RAM |
| OUM | Ovonic Unified Memory |
| PCM | Phase Change Memory |
| PRAM | Phase change RAM |
| PCRAM | Phase Change RAM |
| PMC | Programming Metallization Cell |
| ReRAM | Resistance RAM |
| RRAM | Resistance RAM |

In patent documents, the following words/expressions are often used as synonyms:

- "PMC" and "CBRAM"
- "PRAM", "PCRAM", "PCM", "OUM", "Chalcogenide RAM" and "Ovshinsky-effect memory"
G11C 14/00

Digital stores characterised by arrangements of cells having volatile and non-volatile storage properties for back-up when the power is down {(bistable elements storing the actual state when the supply voltage fails \textit{H03K 3/02335, H03K 3/0375, H03K 3/2865, H03K 3/356008})}

**Definition statement**

\textit{This place covers:}

Memories with arrangements to save information from a volatile to a nonvolatile memory when power supply is lost and to restore the information from the nonvolatile to the volatile memory when power is restored.

Sub-groups cover details of cells adapted for this purpose, classified first by volatile and then by nonvolatile storage type.

**Relationships with other classification places**

For memories where volatile and non-volatile elements co-exist but are operated independently, see \textit{G11C 11/005}. For volatile memories which are designed to power up in a known state (latent image memory), see \textit{G11C 7/20}.

**References**

**Limiting references**

\textit{This place does not cover:}

| Bistable elements storing the actual state when the supply voltage fails | \textit{H03K 3/02335, H03K 3/0375, H03K 3/2865, H03K 3/356008} |

**Special rules of classification**

Where a document only describes the presence of a nonvolatile memory to backup a volatile memory, without cell details, it should be placed in the main group. In principle, a search for such a document would need to encompass all the sub-groups as well as the main group. More detail about the type of storage elements can be added by using Indexing Codes relating to specific cell types.

G11C 14/0009

\{in which the volatile element is a DRAM cell\}

**References**

**Informative references**

\textit{Attention is drawn to the following places, which may be of interest for search:}

| DRAM cells | \textit{G11C 11/401} |

**Special rules of classification**

In case the nonvolatile element is not covered below, classify here with an Indexing Code to specify its type.
G11C 14/0018
{whereby the nonvolatile element is an EEPROM element, e.g. a floating gate or metal-nitride-oxide-silicon [MNOS] transistor}

Special rules of classification
Can further distinguish between FG (Indexing Code G11C 16/0408) and MNOS (Indexing Code: G11C 16/0466).

G11C 14/0027
{and the nonvolatile element is a ferroelectric element}

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

FeRAM cells in general G11C 11/22

G11C 14/0036
{and the nonvolatile element is a magnetic RAM [MRAM] element or ferromagnetic cell}

Special rules of classification
Can be further characterised using codes from Indexing Code G11C 11/14 to Indexing Code G11C 11/16.

G11C 14/0045
{and the nonvolatile element is a resistive RAM element, i.e. programmable resistors, e.g. formed of phase change or chalcogenide material}

Special rules of classification
Can be further characterised using codes from Indexing Code G11C 13/0002 to Indexing Code G11C 13/0019.

G11C 14/0054
{in which the volatile element is a SRAM cell}

Special rules of classification
In case the nonvolatile element is not covered below, classify here with an Indexing Code to specify its type. For SRAM cells in general see G11C 11/41.
G11C 14/0063
{and the nonvolatile element is an EEPROM element, e.g. a floating gate or MNOS transistor}

Special rules of classification
Can further distinguish between FG (Indexing Code G11C 16/0408) and MNOS (Indexing Code G11C 16/0466).

G11C 14/0072
{and the nonvolatile element is a ferroelectric element}

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

FeRAM cells

G11C 14/0081
{and the nonvolatile element is a magnetic RAM [MRAM] element or ferromagnetic cell}

Special rules of classification
Can be further characterised using codes from Indexing Code G11C 11/14 to Indexing Code G11C 11/16.

G11C 14/009
{and the nonvolatile element is a resistive RAM element, i.e. programmable resistors, e.g. formed of phase change or chalcogenide material}

Special rules of classification
Can be further characterised using codes from Indexing Code G11C 13/0002 to Indexing Code G11C 13/0019.

G11C 15/00
Digital stores in which information comprising one or more characteristic parts is written into the store and in which information is read-out by searching for one or more of these characteristic parts, i.e. associative or content-addressed stores (in which information is addressed to a specific location G11C 11/00 {; selection information using addressing means, e.g. hashing, tree addressing, chaining G06F 11/22; information retrieval systems using a computer G06F 16/00 })

Definition statement
This place covers:
Memories wherein a sought data word for a given field (characteristic part) is supplied as input to the memory, which is able to search its stored data contents to determine if the supplied data word is
present among said data contents. If a match or 'hit' is established, the address(es) in the memory where the supplied data word was found is/are returned. Optionally the contents of all fields of the matching word are returned.

References

Limiting references

This place does not cover:

| Digital stores in which information is addressed to a specific location | G11C 11/00 |
| Selection information using addressing means, e.g. hashing, tree addressing, chaining | G06F 11/22 |
| Information retrieval systems using a computer | G06F 16/00 |

Synonyms and Keywords

In patent documents, the following abbreviations are often used:

| CAM | Content Addressable Memory |

G11C 16/00

Erasable programmable read-only memories (G11C 14/00 takes precedence)

Definition statement

This place covers:

Memories of the type in which charge is stored in a non-volatile manner, either in a "floating gate" capacitor (see G11C 16/0408) or trapped in the gate insulator of a transistor (see G11C 16/0466).

In both cases, the effect of charge storage is to modify the threshold voltage of the transistor, e.g. from depletion to enhancement mode (stored state discriminated by conduction or not at zero gate voltage) or from 'normal' to 'deep' enhancement (stored state discriminated by conduction or not at small positive gate voltage).

References

Limiting references

This place does not cover:

| NVRAM Nonvolatile battery backed up RAM | G11C 5/141 |
| Digital stores in which the storage effect is based exclusively on magnetism e.g. Magnetic RAM (MRAM) | G11C 11/15, G11C 11/16 |
| FeRAMs | G11C 11/22 |
| RRAM, ReRAM (Resistive RAM) | G11C 13/0002 - G11C 13/0097 |
| PCRAM, PRAM (Phase-change RAM) | G11C 13/0004 |
| Digital stores characterised by arrangements of cells having volatile and non-volatile storage properties for back-up when the power is down | G11C 14/00 |
| Fabrication of EPROM | H01L21/8247 |
| EPROM memory structures | H01L 27/115 |
**Application-oriented references**

Examples of places where the subject matter of this place is covered when specially adapted, used for a particular purpose, or incorporated in a larger system:

| Use of a cell to back-up the contents of a corresponding volatile memory cell | G11C 14/00 |

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

| Structures of non-volatile memory arrays; individual transistor structures | H01L 27/115, H01L 29/788, H01L 29/792 |

**G11C 16/02**

**electrically programmable { (programmable multibit digital storage elements G11C 11/5621) }**

**References**

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

| Programmable multi-state digital storage elements | G11C 11/5621 |

**G11C 16/0408**

**{comprising cells containing floating gate transistors (G11C 16/0483, G11C 16/0491 take precedence)}**

**Definition statement**

This place covers:

Also cells in which the floating gate is composed of "nanocrystals".

**References**

**Limiting references**

This place does not cover:

| Comprising cells having several storage transistors connected in series | G11C 16/0483 |
| Virtual ground arrays | G11C 16/0491 |
G11C 16/0416
{comprising cells containing a single floating gate transistor and no select transistor, e.g. UV EPROM}

Definition statement
This place covers:
May also comprise cells with additional control gates, e.g. an erase gate.

G11C 16/0425
{comprising cells containing a merged floating gate and select transistor}

Definition statement
This place covers:
The also known as "split-gate" or "1½ transistor" cells.

G11C 16/0433
{comprising cells containing a single floating gate transistor and one or more separate select transistors}

Definition statement
This place covers:
The classical EEPROM cells.

G11C 16/0441
{comprising cells containing multiple floating gate devices, e.g. separate read-and-write FAMOS transistors with connected floating gates}

Definition statement
This place covers:
Aso complementary-pair type cells, in which two floating gate transistors store opposite states. This type is often used to store redundancy information, see also G11C 29/789.

G11C 16/0483
{comprising cells having several storage transistors connected in series}

Definition statement
This place covers:
i.e. NAND type cells.
**G11C 16/0491**

{Virtual ground arrays}

**Definition statement**

*This place covers:*

i.e. arrays in which the individual cell transistors are formed between parallel bitlines, one of which is selected by decoder circuitry to be ground and the other as a normal bitline.

**G11C 16/06**

**Auxiliary circuits, e.g. for writing into memory (in general G11C 7/00)**

**References**

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Details of stores</th>
<th>G11C 5/00</th>
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<td>G11C 7/00</td>
</tr>
<tr>
<td>Arrangements for selecting an address in a digital store</td>
<td>G11C 8/00</td>
</tr>
</tbody>
</table>

**Special rules of classification**

This group is only used if no lower sub-group is suitable - assign multiple sub-groups rather than placing here.

**G11C 16/08**

**Address circuits; Decoders; Word-line control circuits**

**References**

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

| Arrangements for selecting an address in a digital store | G11C 8/00 |
| Word line control circuits, e.g. drivers, boosters, pull-up circuits, pull-down circuits, precharging circuits, for word lines | G11C 8/08 |
| Word line organisation; Word line lay-out | G11C 8/14 |

**G11C 16/10**

**Programming or data input circuits**

**References**

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

| Data input circuits, e.g. write amplifiers, data input buffers, data input registers, data input level conversion circuits | G11C 7/1078 |
G11C 16/107

{Programming all cells in an array, sector or block to the same state prior to flash erasing}

**Definition statement**

*This place covers:*
Erase preprogramming, also called preconditioning.

G11C 16/12

**Programming voltage switching circuits**

**Definition statement**

*This place covers:*
Especially high-voltage switches (see e.g. EP862183, figures 1-3), ramp generators (see e.g. EP903750, figure 4).
References

Informative references

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Ramp generators</th>
<th>H03K 4/00</th>
</tr>
</thead>
<tbody>
<tr>
<td>Switches</td>
<td>H03K 5/003</td>
</tr>
</tbody>
</table>

G11C 16/18

Circuits for erasing optically

Definition statement

This place covers:
e.g. ultra-violet erase.

G11C 16/20

Initialising; Data preset; Chip identification

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Memory initialisation circuits | G11C 7/20 |
G11C 16/22
Safety or protection circuits preventing unauthorised or accidental access to memory cells

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Memory cell safety or protection circuits</th>
<th>G11C 7/24</th>
</tr>
</thead>
<tbody>
<tr>
<td>Address safety or protection circuits</td>
<td>G11C 8/20</td>
</tr>
</tbody>
</table>

G11C 16/225
{Preventing erasure, programming or reading when power supply voltages are outside the required ranges}

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Voltage level detection                   | G11C 5/143 |

G11C 16/24
Bit-line control circuits

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Bit line control circuits</th>
<th>G11C 7/12</th>
</tr>
</thead>
<tbody>
<tr>
<td>Bit line organisation; Bit line lay-out</td>
<td>G11C 7/18</td>
</tr>
</tbody>
</table>

G11C 16/26
Sensing or reading circuits; Data output circuits

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Sense amplifiers; Associated circuits</th>
<th>G11C 7/06</th>
</tr>
</thead>
<tbody>
<tr>
<td>Data output circuits</td>
<td>G11C 7/1051</td>
</tr>
</tbody>
</table>
G11C 16/30
Power supply circuits

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Power supply arrangements | G11C 5/14 |

G11C 16/32
Timing circuits

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Read-write (R-W) timing or clocking circuits; Read-write (R-W) control signal generators or management | G11C 7/22 |
| Address timing or clocking circuits; Address control signal generation or management, e.g. for row address strobe (RAS) or column address strobe (CAS) signals | G11C 8/18 |

G11C 16/3404
{Convergence or correction of memory cell threshold voltages; Repair or recovery of overerased or overprogrammed cells}

Definition statement
This place covers:
What is also known as "overerase/overprogram correction" or "threshold convergence".

G11C 16/3445
{Circuits or methods to verify correct erasure of nonvolatile memory cells}

Definition statement
This place covers:
May lead to repeated erase, verify steps until correctly erased or retry limit reached (= failure).

G11C 16/345
{Circuits or methods to detect overerased nonvolatile memory cells, usually during erasure verification}

Definition statement
This place covers:
Circuits that make no attempt at recovery; the device is therefore regarded as faulty.
G11C 16/3459

{Circuits or methods to verify correct programming of nonvolatile memory cells}

Definition statement

This place covers:
Circuits that may lead to repeated program, verify steps until correctly programmed or retry limit reached (= failure).

G11C 16/3463

{Circuits or methods to detect overprogrammed nonvolatile memory cells, usually during program verification}

Definition statement

This place covers:
Circuits that make no attempt at recovery; the device is therefore regarded as faulty.

G11C 16/349

{Arrangements for evaluating degradation, retention or wearout, e.g. by counting erase cycles}

Synonyms and Keywords

In patent documents, the following abbreviations are often used:

<table>
<thead>
<tr>
<th>Abbreviation</th>
<th>Full Form</th>
</tr>
</thead>
<tbody>
<tr>
<td>EAROM</td>
<td>Electrically-Alterable ROM</td>
</tr>
<tr>
<td>EEPROM, E2PROM</td>
<td>Electrically-Erasable PROM</td>
</tr>
<tr>
<td>EPROM</td>
<td>Erasable PROM</td>
</tr>
<tr>
<td>FAMOS</td>
<td>Floating-gate Avalanche Injection MOS</td>
</tr>
<tr>
<td>M(O)NOS</td>
<td>Metal (Oxide-)Nitride-Oxide Silicon</td>
</tr>
<tr>
<td>S(O)NOS</td>
<td>Silicon (Oxide-)Nitride-Oxide Silicon</td>
</tr>
</tbody>
</table>

In patent documents, the following words/expressions are often used as synonyms:
- "soft programming" (or "soft erasure/erasing"), "overerase (or overprogramming) correction" and "threshold convergence"
G11C 17/00

Read-only memories programmable only once; Semi-permanent stores, e.g. manually-replaceable information cards (multibit read-only memories G11C 11/5692; erasable programmable read-only memories G11C 16/00; coding, decoding or code conversion, in general H03M; combination of ROM and RAM G11C 11/005, G11C 14/00; for electrical control of combustion engines F02D 41/2406)

Definition statement
This place covers:
Memories in which the stored data are permanently defined at the time of manufacturing (mask ROM) or which are adapted to be programmed with data one time only after manufacture (PROM).

References
Limiting references
This place does not cover:

<table>
<thead>
<tr>
<th>Description</th>
<th>Classification</th>
</tr>
</thead>
<tbody>
<tr>
<td>Multibit read only memories</td>
<td>G11C 11/5692</td>
</tr>
<tr>
<td>Rewritable resistive memories (RRAM)</td>
<td>G11C 13/0002</td>
</tr>
<tr>
<td>Erasable programmable read-only memories</td>
<td>G11C 16/00</td>
</tr>
<tr>
<td>Fabrication of read only memories</td>
<td>H01L21/8246</td>
</tr>
<tr>
<td>Read only memory structures</td>
<td>H01L 27/112</td>
</tr>
</tbody>
</table>

Application-oriented references
Examples of places where the subject matter of this place is covered when specially adapted, used for a particular purpose, or incorporated in a larger system:

<table>
<thead>
<tr>
<th>Description</th>
<th>Classification</th>
</tr>
</thead>
<tbody>
<tr>
<td>Combination of ROM and RAM</td>
<td>G11C 11/005, G11C 14/00</td>
</tr>
<tr>
<td>For electrical control of combustion engines</td>
<td>F02D 41/2406</td>
</tr>
</tbody>
</table>

G11C 17/123

{comprising cells having several storage transistors connected in series}

Definition statement
This place covers:
i.e. NAND-type cells.

G11C 17/126

{Virtual ground arrays}

Definition statement
This place covers:
i.e. arrays in which the individual cell transistors are formed between parallel bitlines, one of which is selected by decoder circuitry to be ground and the other as a normal bitline.
**G11C 17/14**

in which contents are determined by selectively establishing, breaking or modifying connecting links by permanently altering the state of coupling elements, e.g. PROM

**Special rules of classification**

So-called OTPROM (one-time programmable read only memories), i.e. EPROMs or flash memory arrays which are wholly or partly adapted to not be erasable (e.g. UV EPROM with no erasing window in the package, flash arrays not selectable to receive erasing voltages) are classified in G11C 16/00, with code G11C 2216/26.

**G11C 17/16**

using electrically-fusible links

**Definition statement**

This place covers:

e.g. fuses, antifuses.

**G11C 17/18**

Auxiliary circuits, e.g. for writing into memory (in general G11C 7/00)

**References**

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

<table>
<thead>
<tr>
<th>Details of stores</th>
<th>G11C 5/00</th>
</tr>
</thead>
<tbody>
<tr>
<td>Arrangements for writing information into, or reading information out from, a digital store</td>
<td>G11C 7/00</td>
</tr>
<tr>
<td>Arrangements for selecting an address in a digital store</td>
<td>G11C 8/00</td>
</tr>
</tbody>
</table>

**Synonyms and Keywords**

In patent documents, the following abbreviations are often used:

<table>
<thead>
<tr>
<th>PROM</th>
<th>Programmable ROM</th>
</tr>
</thead>
<tbody>
<tr>
<td>ROM</td>
<td>Read-only Memory</td>
</tr>
</tbody>
</table>
G11C 19/00
Digital stores in which the information is moved stepwise, e.g. shift register (counting chains H03K 23/00) {stack stores, push-down stores (linear pulse counters H03K 23/54, pulse distributors H03K 5/15, methods and arrangements for shifting data G06F 5/01)}

Definition statement
This place covers:
Digital stores or memories in which information is cascaded between neighbouring data storage locations in a chain under the control of at least one common clock signal.

References
Limiting references
This place does not cover:

| Methods and arrangements for shifting data | G06F 5/01 |
| Pulse distributors                       | H03K 5/15 |
| Counting chains                          | H03K 23/00 |
| Linear pulse counters                    | H03K 23/54 |

G11C 21/00
Digital stores in which the information circulates (continuously) (stepwise G11C 19/00)

Definition statement
This place covers:
Digital stores or memories in which information bits circulate stepwise in a closed loop or ring arrangement.

References
Limiting references
This place does not cover:

| In which information circulates stepwise | G11C 19/00 |

G11C 23/00
Digital stores characterised by movement of mechanical parts to effect storage, e.g. using balls; Storage elements therefor (storing by actuating contacts G11C 11/50)

Definition statement
This place covers:
Micromechanical and nanomechanical systems for data storage.
References

Limiting references
This place does not cover:

Storing by actuating contacts  G11C 11/50

Informative references
Attention is drawn to the following places, which may be of interest for search:

Switches making use of microelectromechanical systems (MEMS)  H01H 1/0036
Switches making use of nanoelectromechanical systems (NEMS)  H01H 1/0094

Glossary of terms
In this place, the following terms or expressions are used with the meaning indicated:

<table>
<thead>
<tr>
<th>Term</th>
<th>Meaning</th>
</tr>
</thead>
<tbody>
<tr>
<td>MEMS</td>
<td>Microelectromechanical systems</td>
</tr>
<tr>
<td>NEMS</td>
<td>Nanoelectromechanical systems</td>
</tr>
</tbody>
</table>

G11C 25/00

Digital stores characterised by the use of flowing media; Storage elements therefor {multiple fluid-circuit element arrangements for performing digital operations  F15C 1/12}

Definition statement
This place covers:
Digital stores or memories whose operation is based on fluid or liquid media.

References

Limiting references
This place does not cover:

Multiple fluid-circuit element arrangements for performing digital operations  F15C 1/12

G11C 27/00

Electric analogue stores, e.g. for storing instantaneous values {integrating circuits acting as stores  G06G 7/18; pulse counters with step by step integration and static storage  H03K 25/00}

Definition statement
This place covers:
Static stores or memories comprising:
• Analogue non-volatile charge storage, under G11C 27/005;
• Sample and hold arrangements, under G11C 27/02, G11C 27/024, G11C 27/026;
• Switched current memories under G11C 27/028;
• Shift registers with analogue charge storage, under G11C 27/04.

**Relationships with other classification places**

**H03K 17/00**: Electronic switching or gating i.e. not by contact-making or -braking.

**H03K 5/13**: Arrangements having a single output and transforming input signals into pulses delivered at desired time intervals.

**References**

**Limiting references**

This place does not cover:

| Integrating circuits acting as stores | G06G 7/18 |
| Pulse counters with step by step integration and static storage | H03K 25/00 |

**Informative references**

Attention is drawn to the following places, which may be of interest for search:

| Digital stores using storage elements with more than two stable states | G11C 11/56 |

**Synonyms and Keywords**

In patent documents, the following abbreviations are often used:

| S/H | Sample and Hold |

In patent documents, the following words/expressions are often used as synonyms:

• "track and hold" and "sample and hold"

**G11C 29/00**

Checking stores for correct operation {; Subsequent repair}; Testing stores during standby or offline operation {testing of electronic circuits in general G01R 31/28; error detection or error correction in computer memories during normal operation G06F 11/1008, G06F 11/1666; testing of computers during standby G06F 11/22}.

**Definition statement**

This place covers:

The two main fields Test and Repair of semiconductor memories.

Concerning Test: This group covers test in particular

• after manufacturing including i.e. wafer test and test of packaged memories at manufacturer;
• after shipping to client and being in use when device is in test mode or performs test during power-on, idle or stand-by state, during refresh cycle.

Repair of memories is found below at G11C 29/70

**Relationships with other classification places**

**H01L**: Semiconductor fabrication means and methods.
**G06F 11/00:** Error detection and correction, monitoring of normal operation.

**G06F 12/00:** Accessing, addressing or allocation within memory systems.

**G01R 31/28:** Test of electronic circuits.

### References

#### Limiting references

*This place does not cover:*

<table>
<thead>
<tr>
<th>Determination of programming status in electrically erasable and programmable read only memories (e.g. for floating gate transistors correction of threshold voltages, recovery of overerased or overprogrammed floating gate transistor cells [G11C 16/3404]; verifying correct erasure or programming of floating gate transistor cells [G11C 16/3436]; evaluation of degradation, retention or wearout of floating gate transistor cells [G11C 16/349]).</th>
<th>G11C 16/34</th>
</tr>
</thead>
<tbody>
<tr>
<td>Test of electronic circuits in general</td>
<td>G01R 31/28</td>
</tr>
<tr>
<td>Test of digital circuits, e.g. separate computer components</td>
<td>G01R 31/317</td>
</tr>
<tr>
<td>Tester hardware in general</td>
<td>G01R 31/319</td>
</tr>
<tr>
<td>Error detection and correction in static stores integrated on a chip of data during normal operation with adding special bits of coded information in memories.</td>
<td>G06F 11/1008</td>
</tr>
<tr>
<td>Error detection or correction of the data by redundancy in hardware where the redundant component is memory or memory area</td>
<td>G06F 11/1666</td>
</tr>
<tr>
<td>Detection of defective computer hardware by testing during stand-by operation or during idle time, e.g. start-up testing.</td>
<td>G06F 11/22</td>
</tr>
<tr>
<td>Interconnection of, or transfer of information or other signals between, memories, input/output devices or central processing units for access to memory bus.</td>
<td>G06F 13/16</td>
</tr>
<tr>
<td>Memory bus transfer protocols</td>
<td>G06F 13/4234</td>
</tr>
<tr>
<td>Test and repair of storage types other than static stores (e.g. rotating disk drives).</td>
<td>G11B</td>
</tr>
<tr>
<td>Test and configuration during manufacture</td>
<td>H01L21/66</td>
</tr>
<tr>
<td>Test of single circuit components not integrated in memory device (e.g. transistors, capacitors) and not individual auxiliary circuits not integrated in memory device (e.g. power supplies, input/output circuitry).</td>
<td>Various classes</td>
</tr>
</tbody>
</table>

#### Informative references

*Attention is drawn to the following places, which may be of interest for search:*

| Tester hardware in general | G01R 31/319 |
| Error detection and correction in static stores integrated on a chip | G06F 11/1008 |
| Error detection and correction in CAM | G06F 11/1064 |
| Error detection and correction in sector programmable memories, flash disks | G06F 11/1068 |
| Error detection and correction in multilevel memories | G06F 11/1072 |
| Details of memory controllers | G06F 13/1668 |
Special rules of classification

Invention related features (concerning testing):

- **G11C 29/02** Detection of defective auxiliary circuits
  
  e.g. short circuit and cross talking on signal lines, intercell defects, stuck at fault (line permanently to GND or Vcc), refresh counter, fuses, charge pumps

  - **G11C 29/021**: in voltage or current generators
  - **G11C 29/022**: in I/O circuitry
  - **G11C 29/023**: in clock generator or timing circuitry
  - **G11C 29/024**: in decoders
  - **G11C 29/025**: in signal lines
  - **G11C 29/026**: in sense amplifiers
  - **G11C 29/027**: in fuses
  - **G11C 29/028**: with adaption or trimming of parameters
    - **G11C 29/04**: Detection of defective memory elements
      - e.g. test of individual cells
      - **G11C 29/06**: Acceleration test
    
    e.g. only when stress (high temperature/voltage/clock frequency) is essential feature - EC documents only classified therein from 2007 onwards (IPC class for mostly Korean and Japanese documents relating to accelerated test)
    - **G11C 29/08**: Functional test
      
      e.g. when test is performed by writing/reading/comparing data, includes stress test (high temperature/voltage/clock frequency) when stress is not essential feature; test when something else is measured, i.e. not by write/read/compare in **G11C 29/50**
    - **G11C 29/10**: Test algorithms and patterns
      
      e.g. checkerboard pattern
      - **G11C 29/12**: Built-in arrangements used for test
        
        e.g. all for which no particular sub-class exists like error catch memory, word/bit line control, identification means, self refresh logic, interconnection details

  - **G11C 29/12005**: comprising voltage or current generators
  - **G11C 29/1201**: comprising IO circuitry
  - **G11C 29/12015**: comprising clock generation or timing circuitry
    - **G11C 29/14**: Control logic
      
      e.g. test configuration, internal clock generation, provisions for high speed test with low speed tester
    - **G11C 29/16**: Microprogrammed control logic
      
      e.g. state machines, sequencers
    - **G11C 29/18**: Address generation, memory access
      
      e.g. address circuits, scrambling
    - **G11C 29/20**: Using counters, linear feedback shift registers
e.g. linear address generation
  • **G11C 29/24** Accessing extra cells, dummy, redundant

e.g. test of redundant cells (replacement of defective cells in **G11C 29/70**)
  • **G11C 29/26** Accessing multiple arrays

e.g. memories with multiple arrays serially accessed
  • **G11C 29/28** Dependent multiple arrays, multi bit

e.g. bit line/word line spans over multiple arrays and is in normal mode accessed at once
  • **G11C 29/30** Accessing single arrays

e.g. test on single array / block
  • **G11C 29/32** Serial access, Scan testing

e.g. cells connected in series only for test (overlap with **G01R 31/318536** scan chain for logic test)
  • **G11C 29/34** Multiple bits

e.g. bit line/word line testing, more than one bit a time tested in single array, word line and bit line driver, controller, decoder therefor
  • **G11C 29/36** Data generation devices

e.g. data storage in DUT, inverters, row copy circuits
  • **G11C 29/38** Response verification devices

e.g. built-in comparators, means to read out test data from memory
  • **G11C 29/40** Using compression techniques

e.g. by use of LFSR (Linear Feedback Shift Register), EXOR logic circuit
  • **G11C 29/42** Using parity or error correction devices

e.g. test performed with use of ECC (overlap with **G06F 11/10**)
  • **G11C 29/44** Identification or indication of errors

e.g. for repair, keep track on found errors, failure capture (overlap with **G06F 11/20**)
  • **G11C 29/4401**: for self repair
  • **G11C 29/46**: Test trigger logic

e.g. initiation of test mode, how to avoid entering test mode
  • **G11C 29/48**: Arrangements to allow test with external means

e.g. inside or outside memory, overlap with 12 and 56, test interfaces, test connectors, probes, I/O lines, reducing number of used pads/terminals to tester, external monitoring of test results, access paths, interface to scan chains, JTAG, DMA, external provided clock for test
  • **G11C 29/50**: Other testing methods

e.g. marginal test including current, race, refresh, temperature, timing/delay, signal margin, imprint and fatigue, floating gate transistor test by dielectric layer test, e.g. gate oxide stress test; EEPROM erase/program verify when focus on threshold voltage or current measurement, i.e. at multilevel EEPROM; charge gain/leakage, DRAM data retention time test, trimming circuits
  • **G11C 29/50004**: of threshold voltage
  • **G11C 29/50008**: of impedance
  • **G11C 29/50012**: of timing
  • **G11C 29/50016**: of retention
e.g. data retention in DRAM or EEPROM cells

• **G11C 29/52** Detection of memory contents errors

e.g. soft errors (i.e. radiation) or when memory content can not be read from outside (content protected), transparent test (modifies contents and restores back to original) EEPROM erase/program verify when 0/1 read (during normal operation **G11C 16/34**) when EEPROM cell is not defective but overerased / overprogrammed

• **G11C 29/54** Design for test tools

e.g. design of test techniques, simulation, test coverage, error latency (probability)

• **G11C 29/56** Tester hardware

  e.g. external test machines, external pattern and address generation/scrambling, here only when specific for memories, overlap with **G01R 31/319**

**G11C 29/56004**: pattern generation

**G11C 29/56008**: error analysis

**G11C 29/56012**: timing aspects, clock generation, synchronisation

**G11C 29/56**: tester apparatus features

• **G11C 29/66** Test of serial memories

  e.g. FIFO, stacks, serial buffers

• **G11C 29/68** Testing at wafer scale level

  e.g. features particular related to wafer test, probing, test circuit location on wafer, e.g. in cut slot, chip identification, IDDQ-test. For test and configuration during manufacturing, see **H01L21/66**.

Additional (not directly invention) related features:

• **G11C 2029/0401** Test of embedded memories

• **G11C 2029/0403** Test during or with feedback to manufacture

e.g. when test result is feedback into manufacturing process

• **G11C 2029/0405** Test circuit comprising complete loop

e.g. document discloses all essential elements off test loop from data generation via DUT to data comparison

• **G11C 2029/0407** Power on test

• **G11C 2029/0409** Online test

e.g. test is performed when memory operates in user application, either in idle state or by monitoring, leading to repair in case of failure

• **G11C 2029/0411** Online error detection and correction

Document relates to error correction (only) in normal operation:

• **G11C 2029/1208** BIST with word line control

• **G11C 2029/1204** BIST with bit line control

• **G11C 2029/1206** Location of test circuitry on chip / wafer

• **G11C 2029/1208** BIST with error catch memory

• **G11C 2029/1802** Test of address decoder

• **G11C 2029/1804** Test with manipulation of data or word size

• **G11C 2029/1806** Test with address conversion/mapping

e.g. translation of logical address to physical address
• **G11C 2029/2602** Concurrent test
e.g. parallel / simultaneous test of multiple word lines / blocks / arrays / devices / modules
  • **G11C 2029/3202** BIST comprising scan chain
  • **G11C 2029/3602** BIST comprising pattern generator
  • **G11C 2029/4002** Comparison of products
e.g. comparison of test results of identical chips or with golden chip; or looping test result through a plurality of chips / modules
  • **G11C 2029/4402** Internal storage of test result related data
e.g. repair information, chip identification, quality data
  • **G11C 2029/5002** Test of characteristic
e.g. physical values not covered elsewhere
  • **G11C 2029/5004** Test of voltage
  • **G11C 2029/5006** Test of current
  • **G11C 2029/5602** Tester interface to DUT
e.g. for timing, voltage, multiplexing of test channels
  • **G11C 2029/5604** Tester with display of error information
e.g. as failure bit map
  • **G11C 2029/5606** Tester comprising error catch memory
e.g. raw data collection and management

**Glossary of terms**

In this place, the following terms or expressions are used with the meaning indicated:

<table>
<thead>
<tr>
<th>Scrubbing</th>
<th>Background test</th>
</tr>
</thead>
<tbody>
<tr>
<td>Automatic test machine</td>
<td>External tester</td>
</tr>
<tr>
<td>Monitoring</td>
<td>Observation of normal operation</td>
</tr>
<tr>
<td>Scrambling, mapping</td>
<td>Translation of a logic address in a physical address or vice versa</td>
</tr>
</tbody>
</table>

**Synonyms and Keywords**

In patent documents, the following abbreviations are often used:

<table>
<thead>
<tr>
<th>ATM</th>
<th>Automatic Test Machine</th>
</tr>
</thead>
<tbody>
<tr>
<td>BISR</td>
<td>Built-In Self-Repair</td>
</tr>
<tr>
<td>BIST</td>
<td>Built-In Self-Test</td>
</tr>
<tr>
<td>DUT, CUT</td>
<td>Device / Cell Under Test</td>
</tr>
<tr>
<td>IDDQ-test</td>
<td>direct current test</td>
</tr>
<tr>
<td>ECC</td>
<td>Error Correction Code</td>
</tr>
<tr>
<td>LFSR</td>
<td>Linear Feedback Shift Register</td>
</tr>
</tbody>
</table>
G11C 29/70
{Masking faults in memories by using spares or by reconfiguring}

Definition statement
This place covers:
Repairing defective memory devices by using redundant (spare) elements; repairing defective memory devices by reconfiguring the address space (this implies a reduced memory capacity compared with a non-defective device); algorithms for effecting such repairs.

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

Error correction in digital computer systems using redundancy

G11C 29/702
{by replacing auxiliary circuits, e.g. spare voltage generators, decoders or sense amplifiers, to be used instead of defective ones}

Definition statement
This place covers:
Illustrative example of subject matter classified in this group: EP1141834, figure 1.
G11C 29/72
{with optimized replacement algorithms}

Definition statement
This place covers:
Replacement algorithms (failure map to redundancy implementation).

G11C 29/76
{using address translation or modifications}

Definition statement
This place covers:
Both with and without dedicated spares - typically address translations via pointers.

Techniques used for redundancy in this kind of applications are always very similar and almost all of them involve sector mapping, counting of read/erase operations, wear-out detection, etc. Many of these documents include lower level features related to flash memories (flash).

Special rules of classification
See also G11C 16/349 for wear-out detection; G11C 29/88 for 'hard wired' reconfiguration.

G11C 29/78
{using programmable devices}

Definition statement
This place covers:
Could include disconnecting faulty elements.

G11C 29/783
{with refresh of replacement cells, e.g. in DRAMs}

Definition statement
This place covers:
In DRAMS, how to refresh the redundant lines which are substituting faulty lines.

G11C 29/785
{with redundancy programming schemes}

Definition statement
This place covers:
Fuse related issues; most of these documents have descriptions at transistor level, explaining how the fuse circuits are built or how they are included in the redundancy decoding elements.
G11C 29/787
{using a fuse hierarchy (for memories using fuses in general G11C 17/16)}

Definition statement

This place covers:

In this case, a master fuse can be used to decide whether a redundant line or decoder is in use. This allows to save time when programming the fuses. See EP646866, fig.3 (reference 50).

References

Informative references

Attention is drawn to the following places, which may be of interest for search:

| Memories using fuses in general | G11C 17/16 |
G11C 29/789
{using non-volatile cells or latches (erasable programmable memory cells in general G11C 16/00)}

Definition statement
This place covers:
In these documents, the "fuse" is not a fuse as such, but rather a non-volatile memory cell or a combination of a fuse with a latch to retain its status (i.e. the fuse is only read at power up to reduce stress thereon). See US5619469, fig2.

References
Informative references
Attention is drawn to the following places, which may be of interest for search:

| Erasable programmable memory cells in general | G11C 16/00 |

G11C 29/80
{with improved layout}

Definition statement
This place covers:
Under this group, techniques which tend to reduce real estate by several means. When the document is a pure layout description - i.e. without a clear functionality other than a "new layout" - it is included in this 'head group'. It should be clear that there is a clear "layout" approach in the description and figures.
Definition statement

This place covers:
Transmission of faulty/redundant addresses between the fuse boxes and the final decoders is done by encoding: For 2n redundant lines only n lines have to be routed. See EP496282, fig.2.
G11C 29/804
{to prevent clustered faults}

Definition statement

This place covers:
Faults which involve several (adjacent) lines can be solved in a simplified way, 'simplified' implying using a reduced amount of coding or storage for the defect. These kind of faults are very frequent due to impurities of a big size. See US5281868, fig. 3,4.

FIG. 3

FIG. 4
G11C 29/806
{by reducing size of decoders}

Definition statement

This place covers:
Solutions that might have a lower redundancy efficiency (e.g. lines can only be replaced in sets of four, regardless of the fault) but allows to have fewer and/or smaller comparators. See EP239196, fig 3.

G11C 29/808
{using a flexible replacement scheme}

Definition statement

This place covers:
All kinds of solutions in which different combinations of faulty/redundant replacement are possible to allow for a higher level of repair with a lower number of spares. For instance, when redundant lines in
a block can be used to substitute faulty lines in any other block, or when the same redundant line can be used for row or column repair, etc. See US5469388 fig 4A.

**G11C 29/81**

*{using a hierarchical redundancy scheme}*

**Definition statement**

*This place covers:*

Faults are solved in a hierarchical way. For instance: lines are replaced with redundant lines in a given block or, if not possible, then the complete block is repaired with a redundant block as a whole unit, etc. See US5295101, fig. 7.

**G11C 29/812**

*{using a reduced amount of fuses}*

**Definition statement**

*This place covers:*

The amount of real estate occupied by fuses is lower.
**G11C 29/814**

{for optimized yield}

**Definition statement**

*This place covers:*

The layout is done in such a way that a certain cost function associated with the yield is optimized. A lot of NPL and thesis-like stuff. See XP237814.

**G11C 29/816**

{for an application-specific layout}

**Definition statement**

*This place covers:*

Certain applications (ROMs, synchronous memories, cache memories) demand redundancy solutions which are very related to the nature of the application itself and therefore more likely to be relevant in an application-oriented context.

**G11C 29/818**

{for dual-port memories}

**Definition statement**

*This place covers:*

For the case of Dual port RAMs, video memories and the like.

**G11C 29/82**

{for EEPROMs}

**Definition statement**

*This place covers:*

These redundancy solutions are usually taking into account the block erase operations as well as the aging of EEPROM cells due to program/erase. Many of these documents are also classified with the solid state disks solutions (G11C 29/765). Normally documents put in this group work at a lower level (i.e. row/columns in a block, rather than sector mapping level.

**G11C 29/822**

{for read only memories}

**Definition statement**

*This place covers:*

Redundancy solutions for Mask ROMs which have specific layouts.
G11C 29/824

{for synchronous memories}

Definition statement

This place covers:
Same as above for the case of synchronous memories. Timing (synchronicity) requirements as well as the specific (i.e. sequential) nature of read/write operations are linked to some redundancy requirements.

G11C 29/83

{with reduced power consumption}

Definition statement

This place covers:
Most of the solutions for this problem are related to the avoidance of DC faults.

G11C 29/832

{with disconnection of faulty elements}

Definition statement

This place covers:
A common way to reduce power consumption in these cases.

G11C 29/835

{with roll call arrangements for redundant substitutions}

Definition statement

This place covers:
Roll call circuits to identify redundancy substitutions.

G11C 29/838

{with substitution of defective spares}

Definition statement

This place covers:
Solving the problem of a faulty spare element which must be disabled for redundant substitution.

G11C 29/84

{with improved access time or stability}

Definition statement

This place covers:
In this group, solutions which propose to eliminate or reduce the difference in speed between a non-faulty and a faulty line selection. Many of these documents are actually addressing stability problems
(e.g. obtain a reliable voltage level before sampling fuse values) employing similar solutions such as ATDs.

**G11C 29/842**

*by introducing a delay in a signal path*

**Definition statement**

*This place covers:*

The trick here usually is to insert a delay element in the faster path to make sure both paths (normal and redundant) are equally slow. This delay element usually consists of slower transistors in the path or a chain of inverters. See US5777931, fig.5.

**G11C 29/844**

*by splitting the decoders in stages*

**Definition statement**

*This place covers:*

A normal/redundant selection signal is already obtained at a predecoding stage which allows to start some kind of preselection. See US5550776, fig.4.
G11C 29/846

{by choosing redundant lines at an output stage}

**Definition statement**

_This place covers:_

Usually the case with column redundancy: Addresses are input simultaneously to faulty and normal column decoders and only at the output (usually by means of a multiplexer) it is decided whether a redundant replacement is pertinent. See US4473895, fig.1.
**G11C 29/848**

(by adjacent switching)

**Definition statement**

*This place covers:*

Columns are shifted one or more position skipping the faulty one(s). There are redundant columns at the end of the chain. See EP434200, fig. 4.

**G11C 29/88**

{with partially good memories}

**Definition statement**

*This place covers:*

Partially good memories, degraded memories.

**Synonyms and Keywords**

*In patent documents, the following abbreviations are often used:*

<table>
<thead>
<tr>
<th>Abbreviation</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>DEP</td>
<td>Defective end product; (now G11C 29/883)</td>
</tr>
<tr>
<td>CDEP</td>
<td>Combining defective end product. (now G11C 29/886)</td>
</tr>
</tbody>
</table>
G11C 2229/723
Redundancy information stored in a part of the memory core to be repaired

Definition statement
This place covers:
See US2006190762 (figure 1 - shown), US2009067276.

Fig. 1
G11C 2229/726

Redundancy information loaded from the outside into the memory

Definition statement

This place covers:

See US2008307251 (fig.1), US2009072886 (fig.1 - shown).
**G11C 2229/746**

**Before packaging**

**Definition statement**

This place covers:

See US2006221729, figure 2.
G11C 2229/766

Laser fuses

Definition statement

This place covers:

See US2008180983 (figure 2), US2006221729 (figure 3).